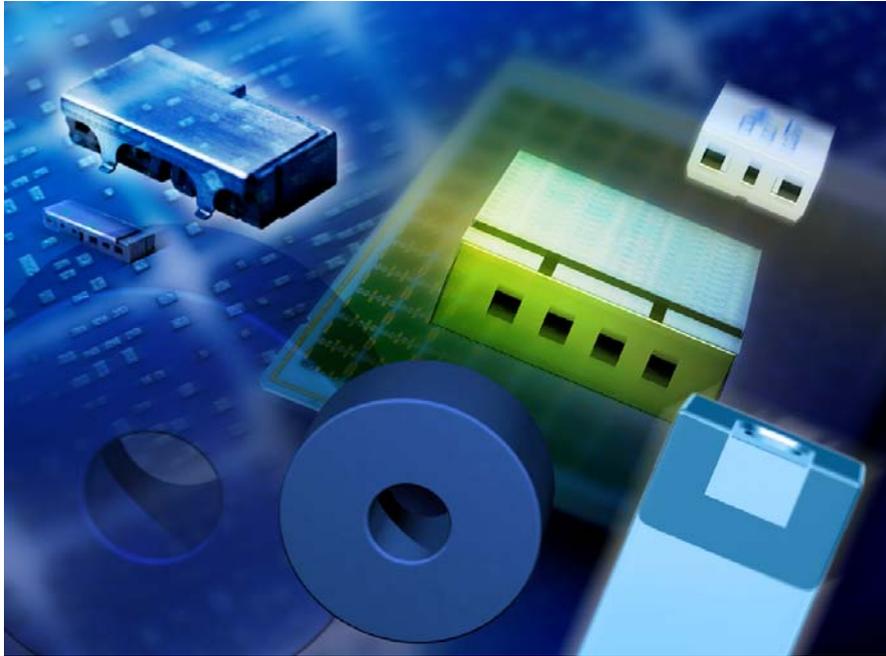


Preliminary Data Sheet



**Features**

- Small Dimensions (3mm x 2.8mm x 2mm)
- Low Losses in Passband (typ. 1.5dB)
- High attenuations at GSM, PDC, PHS, UMTS, and WLAN Bands
- Excellent reflow solderability, no migration effect due to copper/tin metallization

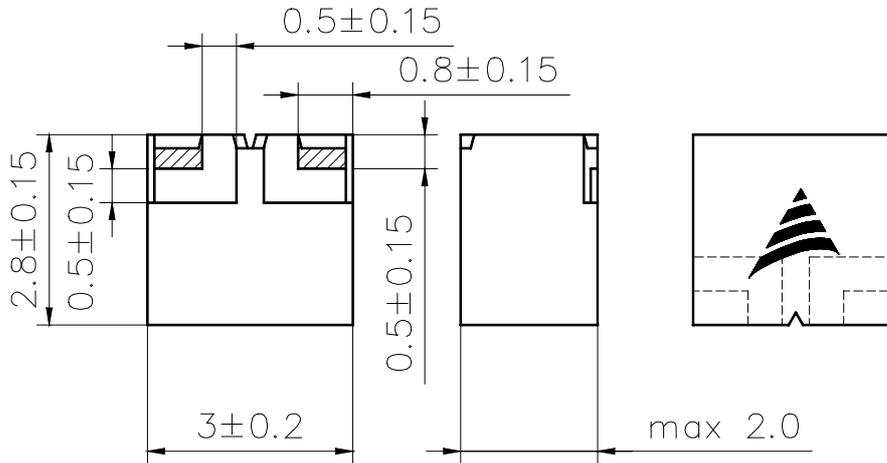
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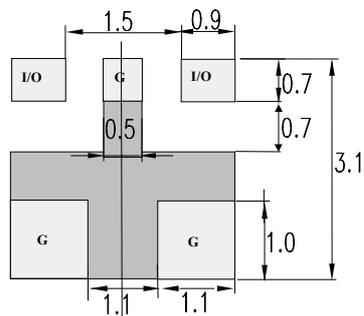
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Dimension Limits



Recommended Footprint



 Solder Pads:  
I/O Pads must be connected to lines with 50 Ω impedance. In the application a termination of 50 Ω must be realized.

 Ground, covered with solder resist, connected to lower ground plane by vias with maximum diameter of 0.3mm and max. distance of 1mm

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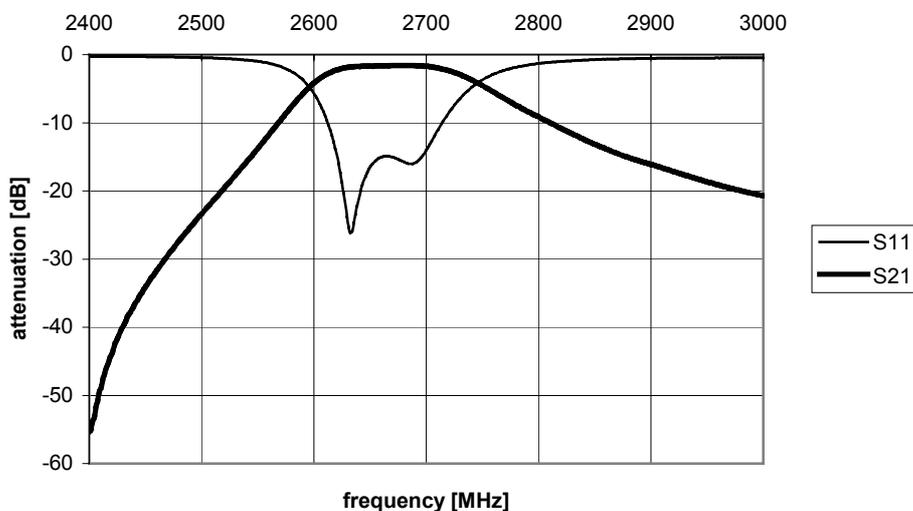
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Characteristics (over whole temperature range)		min.	typ.	max.	
Center frequency	$f_c$	-	2.6425	-	GHz
Insertion loss	$\alpha_{IL}$		1.5	2.0	dB
Passband (2629- 2656)	$B$	27			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.1	0.3	dB
Standing Wave Ratio / Return Loss [dB]			1.5 / -14	2.0 / -9.5	
Impedance	$Z$		50		$\Omega$
Attenuation	$\alpha$				
at DC to 440 MHz		57	>70		dB
at 440 to 1525 MHz		32	45		dB
at 1525 to 1680 MHz		40	45		dB
at 1680 to 1980 MHz		35	40		dB
at 1980 to 2170 MHz		32	35		dB
at 2170 to 2500 MHz		22	25		dB
at 3450 MHz		30	35		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40 /+ 90/56	
Operating temperature	$T_{Op}$	- 40 / + 85	°C

Typical passband characteristics



Preliminary Data Sheet

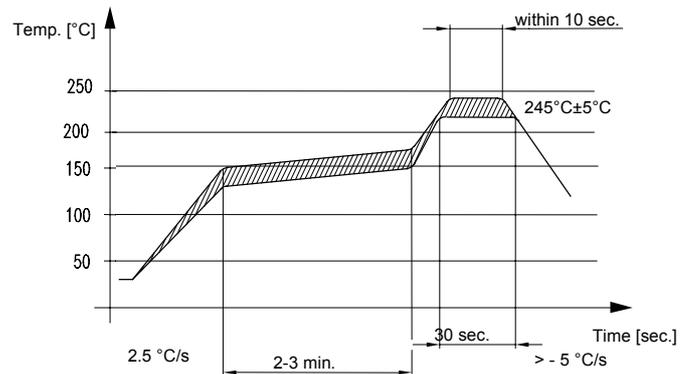
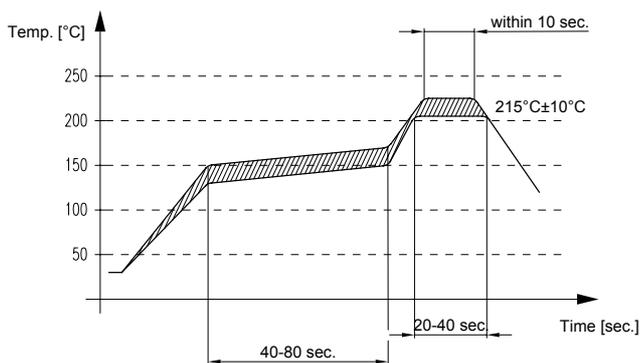
**Processing information**

Wettability acc.to IEC 68-2-58:  $\geq 75\%$  (after aging)

**Soldering Requirements**

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	$^{\circ}\text{C}$ $^{\circ}\text{C}$

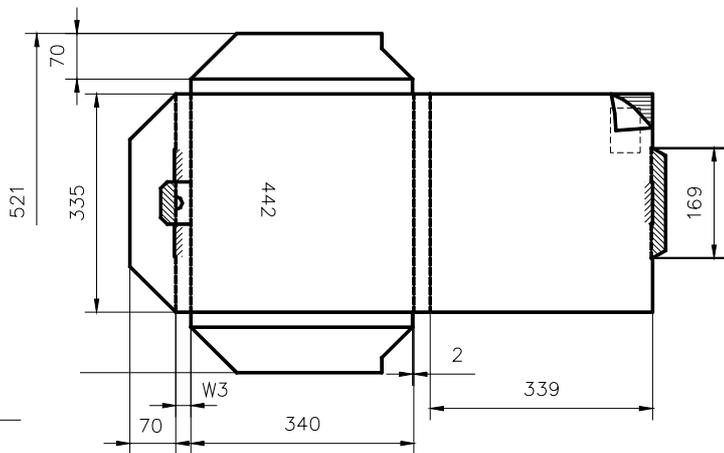
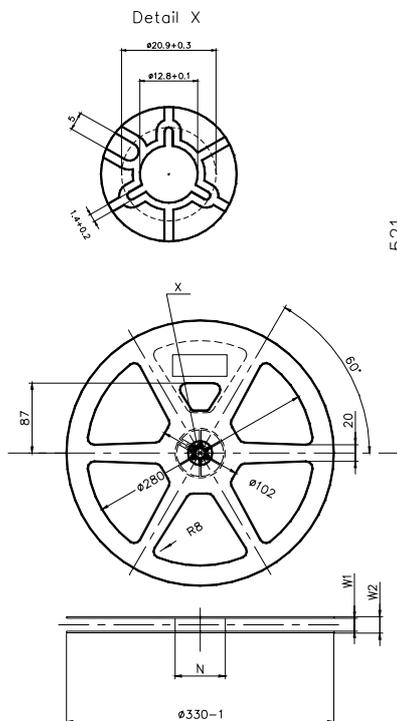
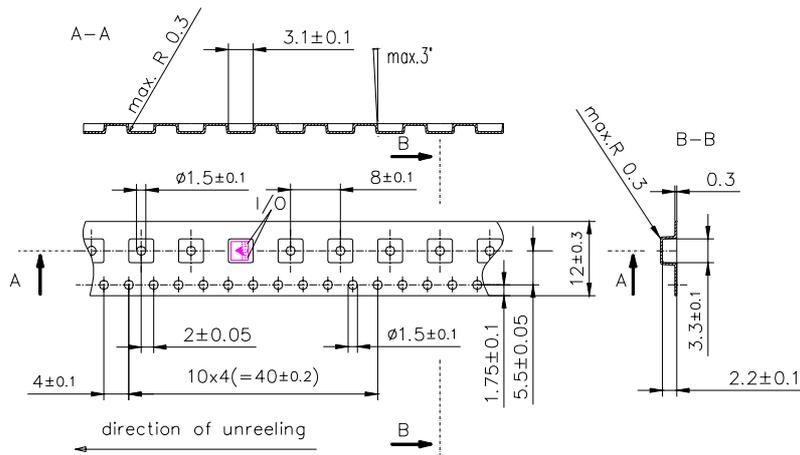
Recommended soldering conditions (infrared):



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Delivery mode

- Blister tape acc. to IEC 286-3, grey
- Pieces/tape: **4000**



$W1 = 13 \text{ mm}$   
 $W2 = 17 \text{ mm}$   
 $W3 = 23 \text{ mm}$   
 $N = 62 \text{ mm}$

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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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